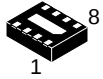


MECHANICAL CASE OUTLINE

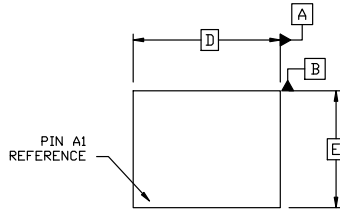
PACKAGE DIMENSIONS



SCALE 4:1

UDFN8, 1.7x1.35, 0.4P
CASE 517BC
ISSUE A

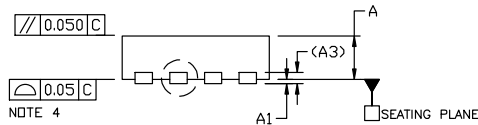
DATE 11 AUG 2022



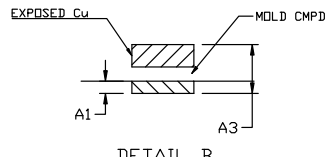
TOP VIEW

NOTES:

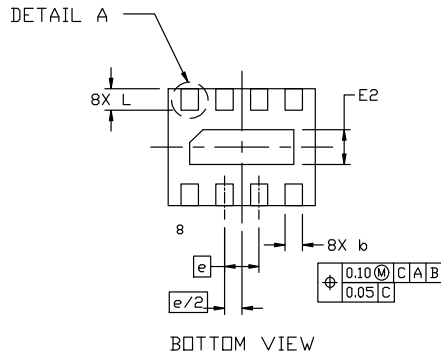
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2004.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25MM FROM THE TERMINAL TIP.
4. COPLANAR[⋄]



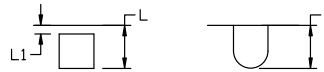
SIDE VIEW



DETAIL B
ALTERNATE CONSTRUCTIONS



BOTTOM VIEW



DETAIL A
ALTERNATE CONSTRUCTIONS

	MAX.	
A3	0.13	REF
A3	0.15	0.25
	1.70 BSC	
D2	1.10	1.30
E	1.35	BSC
E2	0.30	0.50
K	0.15	---
L1	---	0.05

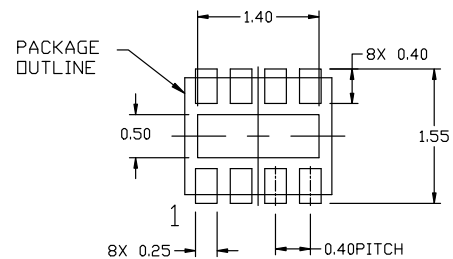
GENERIC MARKING DIAGRAMS*



XXX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT*

* For additional information on our Pb-Free strategy and soldering details, please download the QN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.